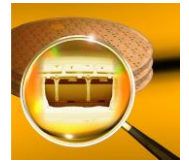




# IEEE 3DIC 2024



IEEE International 3D Systems Integration Conference  
September 25<sup>th</sup> – 27<sup>th</sup>, 2024, Sendai, Japan

## 3<sup>rd</sup> Call for Papers

The IEEE International 3D Systems Integration Conference (3DIC) will be held at the Hotel Metropolitan Sendai and Sendai Kokusai Hotel in Sendai, Japan, September 25<sup>th</sup>-27<sup>th</sup>, 2024. The deadline for abstract submission is ***June 30, 2024***.

Abstracts should be 1 page text (500 words) and 1 page figures.

**3DIC 2024** will cover all **3D system integration** topics, including 3D/Chiplet process technology, materials, equipment, circuits technology, design methodology, and applications. The conference invites authors and attendees to submit and interact with researchers from all around the world. Papers are solicited in subject topics, including, but not limited to, the following:

**3D/Chiplet Integration Technology:** Through-Si Vias (TSV), Hybrid bonding, Wafer thinning, Wafer/Chip alignment, WtW/WtC/CtC bonding, Wafer dicing, Interposer (Si/Glass/Organic), Optical interconnect, FOWLP, Monolithic 3D integration, Heterogeneous integration, and Chiplet technology

**3D/Chiplet Circuits Technology:** SoC, 3D NAND, HBM, CPU/GPU, DSP, FPGA, ASIC, RF and mm-wave, Analog circuits, Biomedical circuits, and Chiplet design

**3D/Chiplet Applications:** Artificial Intelligence, Quantum Computing, Post 5G/6G, Intelligent Sensor Systems, Bio/Medical Imaging, and VR/AR

**3D/Chiplet Design and Test Methodology:** CAD, Synthesis, Design flows, Signal and power integrity analysis and design in 3D/Chiplet, Thermal design and analysis, Test and design for test, Mechanical stress and reliability design and analysis

### 2024 Conference Co-Chairs:

T. Tanaka (Tohoku Univ), P. Franzon (NCSU)

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**Conference website:** [www.3dic-conf.org](http://www.3dic-conf.org)

